

1. (Amended) A semiconductor package for enhancing heat

sub
CIP
dissipation, comprising:

a die having an active surface;

a leadframe, including:

a die pad having a first surface and a second surface, said die being attached to said first surface of the die pad; and

a plurality of leads electrically connected to the active surface of said die, said leads having a surface;

an encapsulant sealing said die and at least a portion of the surface of the leads in said leadframe; and

a heat sink attached to the second surface of said die pad and at least a portion of the surface of leads in said plurality of leads with a thermally conductive and electrically insulating adhesive glue, said heat sink being exposed to ambient atmosphere and not encapsulated in said encapsulant.

REMARKS

Careful consideration has been given to the Official Action of November 8, 2002 and reconsideration of the application is respectfully requested.

Claim 1 has been amended to correct a typographical error.